SN54ABT162600 . . . WD PACKAGE SN74ABT162600 . . . DL PACKAGE

(TOP VIEW)

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- B-Port Outputs Have Equivalent 25-Ω Series Resistors, So No External Resistors Are Required
- **Members of the Texas Instruments** Widebus™ Family
- State-of-the-Art *EPIC-IIB* ™ BiCMOS Design **Significantly Reduces Power Dissipation**
- UBT™ (Universal Bus Transceiver) **Combines D-Type Latches and D-Type** Flip-Flops for Operation in Transparent, Latched, Clocked, or Clock-Enabled Mode
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V<sub>OLP</sub> (Output Ground Bounce) < 0.8 V at  $V_{CC} = 5 \text{ V}, T_A = 25^{\circ}\text{C}$
- Flow-Through Architecture Optimizes **PCB Layout**
- Packaged in Plastic 300-mil Shrink Small-Outline Packages and 380-mil Fine-Pitch Ceramic Flat Packages Using 25-mil Center-to-Center Spacings

#### description

These 18-bit universal bus transceivers combine D-type latches and D-type flip-flops to allow data flow in transparent, latched, and clocked modes.

56 CLKENAB OEAB LEAB 2 55 CLKAB A1 🛚 3 54 B1 GND 4 53 GND A2 🛮 5 52 B2 A3 6 51 B3 50 V<sub>CC</sub> V<sub>CC</sub> **↓** 7 A4 🛮 8 49 B4 48 ¶ B5 A5 | 9 A6 II 10 47 ∏ B6 GND [] 11 46 GND A7 🛮 12 45 **∏** B7 44 N B8 A8 🛮 13 A9 🛮 14 43 **□** B9 A10 15 42**∏** B10

> GND II 18 39 **∏** GND A13 19 38 **∏** B13 A14 20 37 B14 A15 21 36 B15 V<sub>CC</sub> 📙 22 35 V<sub>CC</sub> A16 23 34 🛮 B16 A17 🛮 24 33 **∏** B17

41 ∏ B11

40**∏** B12

A11 🛮 16

A12 1 17

GND 25 32 GND A18 26 31 **∏** B18 30 CLKBA OEBA 27 LEBA 28 29 CLKENBA

Data flow in each direction is controlled by output-enable ( $\overline{OEAB}$  and  $\overline{OEBA}$ ), latch-enable (LEAB and LEBA), and clock (CLKAB and CLKBA) inputs. The clock can be controlled by the clock-enable (CLKENAB and CLKENBA) inputs. For A-to-B data flow, the device operates in the transparent mode when LEAB is high. When LEAB is low, the A data is latched if CLKAB is held at a high or low logic level. If LEAB is low, the A-bus data is stored in the latch/flip-flop on the high-to-low transition of CLKAB. Output-enable OEAB is active-low. When OEAB is low, the outputs are active. When OEAB is high, the outputs are in the high-impedance state. Data flow for B to A is similar to that of A to B but uses OEBA, LEBA, CLKBA, and CLKENBA.

The B-port outputs, which are designed to source or sink up to 12 mA, include  $25-\Omega$  series resistors to reduce overshoot and undershoot.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74ABT162600 is available in TI's shrink small-outline package (DL), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The SN54ABT162600 is characterized over the full military temperature range of −55°C to 125°C. The SN74ABT162600 is characterized for operation from -40°C to 85°C.

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#### **FUNCTION TABLE**†

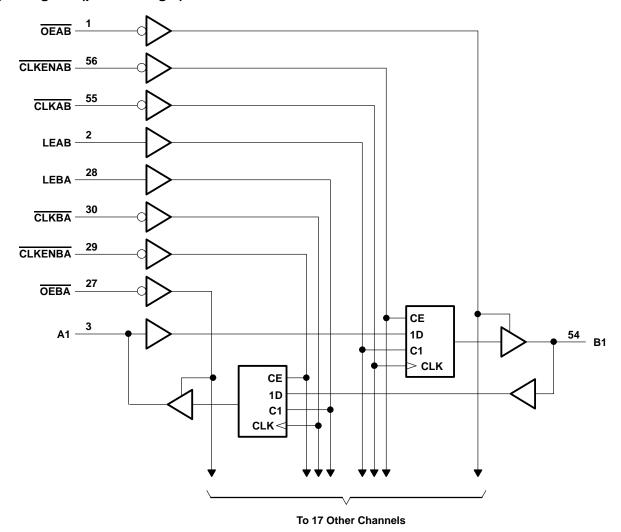
	OUTPUT				
CLKENAB	OEAB	LEAB	CLKAB	Α	В
Х	Н	Х	Х	Χ	Z
Х	L	Н	Χ	L	L
Х	L	Н	Χ	Н	Н
Н	L	L	Χ	Χ	в <sub>0</sub> ‡
Н	L	L	Χ	Χ	в <sub>0</sub> ‡ в <sub>0</sub> ‡
L	L	L	$\downarrow$	L	L
L	L	L	$\downarrow$	Н	Н
L	L	L	Н	Χ	в <sub>0</sub> ‡
L	L	L	L	Χ	В <sub>0</sub> §

<sup>†</sup> A-to-B data flow is shown: B-to-A flow is similar but uses  $\overline{\text{OEBA}}$ , LEBA,  $\overline{\text{CLKBA}}$ , and  $\overline{\text{CLKENBA}}$ .

<sup>&</sup>lt;sup>‡</sup> Output level before the indicated steady-state input conditions were established.

<sup>§</sup> Output level before the indicated steady-state input conditions were established, provided that CLKAB was low before LEAB went low.

#### logic diagram (positive logic)



# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	
Input voltage range, V <sub>I</sub> (except I/O ports) (see Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high state or power-off state, VO	−0.5 V to 5.5 V
Current into any output in the low state, IO: SN54ABT162600 (A port)	96 mA
SN74ABT162600 (A port)	128 mA
B port	30 mA
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	–18 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)	–50 mA
Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air)	1 W
Storage temperature range	. −65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.



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#### recommended operating conditions (see Note 2)

			SN54AE	T162600	SN74ABT162600		ш	
			MIN	MAX	MIN	MAX	UNIT	
Vсс	Supply voltage	4.5	5.5	4.5	5.5	V		
VIH	High-level input voltage				2		V	
VIL	Low-level input voltage			8.0		0.8	V	
٧ <sub>I</sub>	Input voltage	0	Vcc	0	Vcc	V		
ЮН	High-level output current	A port		-24		-32	mA	
	High-level output current	B port		-12		-12	IIIA	
loL	Low level output ourrest	A port		48		64		
	Low-level output current	B port		12		12	mA	
Δt/Δν	Input transition rise or fall rate	Outputs enabled		10		10	ns/V	
TA	Operating free-air temperature		-55	125	-40	85	°C	

NOTE 2: Unused or floating pins (input or I/O) must be held high or low.



# PRODUCT PREVIEW

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T <sub>A</sub> = 25°C			SN54ABT162600		SN74ABT162600		UNIT
	KAMEIER	TEST CONDITIONS		MIN	TYP†	MAX	MIN	MAX	MIN	MAX	UNII
VIK		$V_{CC} = 4.5 \text{ V},$	I <sub>I</sub> = -18 mA			-1.2		-1.2		-1.2	V
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5		v
	A port	$V_{CC} = 5 V$ ,	$I_{OH} = -3 \text{ mA}$	3			3		3		
	A port	$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -24 \text{ mA}$	2			2				
\/o		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -32 \text{ mA}$	2‡					2		
VOH		$V_{CC} = 4.5 \text{ V},$	I <sub>OH</sub> = – 1 mA	3.35			3.3		3.35		
	B port	$V_{CC} = 5 V$ ,	$I_{OH} = -1 \text{ mA}$	3.85			3.8		3.85		
	B poit	$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	3.1			3		3.1		
		$V_{CC} = 4.5 \text{ V},$	I <sub>OH</sub> = – 12 mA	2.6					2.6		
	A port	V00 = 4.5.V	I <sub>OL</sub> = 48 mA			0.55		0.55			V
VOL	A port	V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 64 mA			0.55‡				0.55	
	B port	$V_{CC} = 4.5 \text{ V},$	I <sub>OL</sub> = 12 mA			0.8		0.8		0.8	
ļ.,	Control inputs	V <sub>CC</sub> = 5.5 V,				±1		±1		±1	μΑ
lj .	A or B ports	$V_I = V_{CC}$ or GND				±20		±20		±20 μ.	
IOZH§		$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 2.7 V			10		10		10	μΑ
IOZL§		$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 0.5 V			-10		-10		-10	μΑ
l <sub>off</sub>		$V_{CC} = 0$ ,	$V_I$ or $V_O \le 4.5 \text{ V}$			±100				±100	μΑ
ICEX		V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 5.5 V	Outputs high			50		50		50	μΑ
. «	A port	$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 2.5 V	-50	-100	-180	-50	-180	-50	-180	mA
IO¶	B port	V <sub>CC</sub> = 5.5 V	V <sub>O</sub> = 2.5 V	-25	-55	-100	-25	-100	-25	-100	IIIA
	A or B ports	V <sub>CC</sub> = 5.5 V,	Outputs high			3		3		3	mA
ICC			Outputs low			36		36		36	
			Outputs disabled			3		3		3	
Δl <sub>CC</sub> #		V <sub>CC</sub> = 5.5 V, One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND  50		50	μΑ						
Ci	Control inputs	V <sub>I</sub> = 2.5 V or 0.5 V			3						pF
C <sub>io</sub>	A or B ports	$V_0 = 2.5 \text{ V or } 0.5 \text{ V}$	/		9						pF

 $<sup>\</sup>dagger$  All typical values are at  $V_{CC} = 5 \text{ V}$ .

<sup>‡</sup> On products compliant to MIL-STD-883, Class B, this parameter does not apply.

<sup>§</sup> The parameters IOZH and IOZL include the input leakage current.

<sup>¶</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

 $<sup>^{\#}</sup>$  This is the increase in supply current for each input that is at the specified TTL voltage level rather than  $V_{CC}$  or GND.

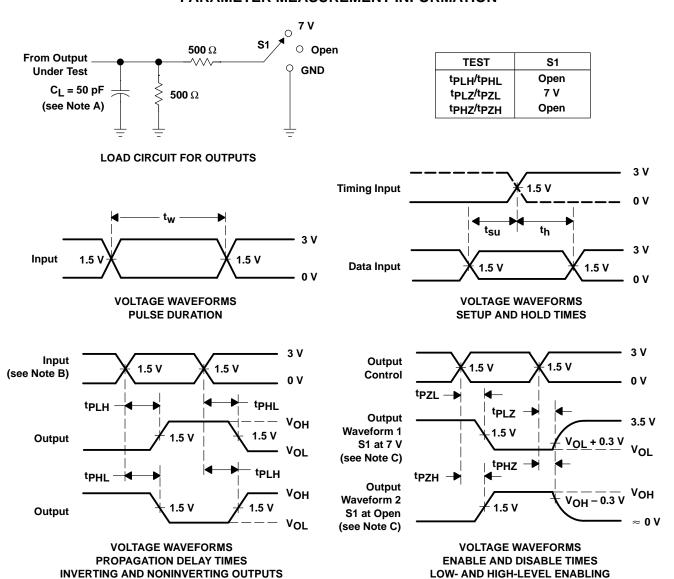
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timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

				SN54ABT162600 MIN MAX		SN74ABT162600		UNIT
						MIN	MAX	UNII
fclock	Clock frequency			0	150	0	150	MHz
	Pulse duration	LEAB or LEBA high					20	
t <sub>W</sub>	Puise duration	CLKAB or CLKBA high or low			ns			
	Catura tima	A before CLKAB↓					ns	
		B before CLKBA↓						
t <sub>su</sub>	Setup time	A before LEAB↓ or B before LEBA↓	CLK high					115
		CLK lo	CLK low					
4.	Hold time	A after CLKAB↓ or B after CLKBA↓						20
<sup>t</sup> h	Holu lille	A after LEAB↓ or B after LEBA↓						ns



#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $t_f \leq$  2.5 ns,  $t_f \leq$  2.5 ns.
- C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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